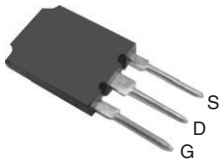
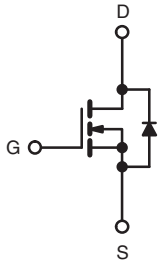
Power MOSFET

Super-247





N-Channel MOSFET

FEATURES

- Low gate charge Q_g results in simple drive requirement
- Improved gate, avalanche and dynamic dV/dt ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Effective C_{oss} specified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Pb-free

RoHS COMPLIANT

HALOGEN FREE

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching

TYPICAL SMPS TOPOLOGIES

- Full bridge converters
- Power factor correction boost

PRODUCT SUMMARY		
V_{DS} (V)	500	
$R_{DS(on)}$ (Max.) (Ω)	V_{GS} = 10 V	0.13
Q_g (Max.) (nC)	180	
Q_{gs} (nC)	46	
Q_{gd} (nC)	71	
Configuration	Single	

ORDERING INFORMATION	
Package	Super-247
Lead (Pb)-free and halogen-free	SiHFPS37N50A-GE3

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	500	V
Gate-source voltage			V_{GS}	± 30	
Continuous drain current	V_{GS} at 10 V	T_C = 25 °C	I_D	36	A
		T_C = 100 °C		23	
Pulsed drain current [a]			I_{DM}	144	
Linear derating factor				3.6	W/°C
Single pulse avalanche energy [b]			E_{AS}	1260	mJ
Repetitive avalanche current [a]			I_{AR}	36	A
Repetitive avalanche energy [a]			E_{AR}	44	mJ
Maximum power dissipation	T_C = 25 °C		P_D	446	W
Peak diode recovery dV/dt [c]			dV/dt	3.5	V/ns
Operating junction and storage temperature range			T_J, T_{stg}	- 55 to + 150	°C
Soldering recommendations (peak temperature)	for 10 s			300 [d]	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. Starting T_J = 25 °C, L = 1.94 mH, R_g = 25 Ω, I_{AS} = 36 A (see fig. 12)

c. $I_{SD} \leq$ 36 A, dI/dt ≤ 145 A/µs, $V_{DD} \leq V_{DS}$, $T_J \leq$ 150 °C

d. 1.6 mm from case

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum junction-to-ambient	R_{thJA}	-	40	°C/W
Case-to-sink, flat, greased surface	R_{thCS}	0.24	-	
Maximum junction-to-case (drain)	R_{thJC}	-	0.28	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static							
Drain-source breakdown voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA		500	-	-	V
Gate-source threshold voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA		2.0	-	4.0	V
Gate-source leakage	I_{GSS}	V_{GS} = ± 30 V		-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	V_{DS} = 500 V, V_{GS} = 0 V		-	-	25	µA
		V_{DS} = 400 V, V_{GS} = 0 V, T_J = 150 °C		-	-	250	
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS} = 10 V	I_D = 22 A [b]	-	-	0.13	Ω
Forward transconductance	g_{fs}	V_{DS} = 50 V, I_D = 22 A [b]		20	-	-	S
Dynamic							
Input capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	5579	-	pF
Output capacitance	C_{oss}			-	810	-	
Reverse transfer capacitance	C_{rss}			-	36	-	
Output capacitance	C_{oss}	V_{GS} = 0 V	V_{DS} = 1.0 V, f = 1.0 MHz	-	7905	-	
			V_{DS} = 400 V, f = 1.0 MHz	-	221	-	
Effective output capacitance	C_{oss} eff.		V_{DS} = 0 V to 400 V	-	400	-	
Total gate charge	Q_g	V_{GS} = 10 V	I_D = 36 A, V_{DS} = 400 V, see fig. 6 and 13 [b]	-	-	180	nC
Gate-source charge	Q_{gs}			-	-	46	
Gate-drain charge	Q_{gd}			-	-	71	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 250 V, I_D = 36 A, R_G = 2.15 Ω, R_D = 7.0 Ω, see fig. 10 [b]		-	23	-	ns
Rise time	t_r			-	98	-	
Turn-off delay time	$t_{d(off)}$			-	52	-	
Fall time	t_f			-	80	-	
Drain-source body diode characteristics							
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	36	A
Pulsed diode forward current [a]	I_{SM}			-	-	144	
Body diode voltage	V_{SD}	T_J = 25 °C, I_S = 36 A, V_{GS} = 0 V [b]		-	-	1.5	V
Body diode reverse recovery time	t_{rr}	T_J = 25 °C, I_F = 36 A, dI/dt = 100 A/µs [b]		-	570	860	ns
Body diode reverse recovery charge	Q_{rr}			-	8.6	13	µC
Forward turn-on time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %

c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

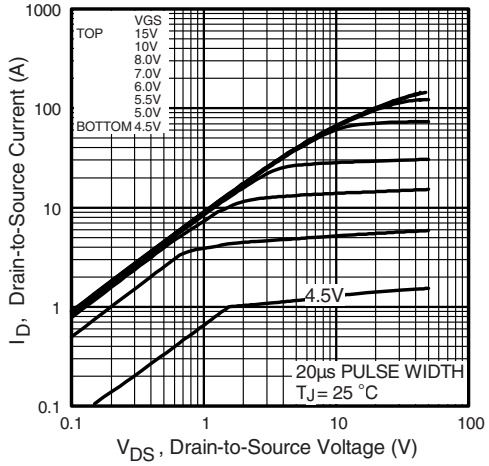


Fig. 1 - Typical Output Characteristics

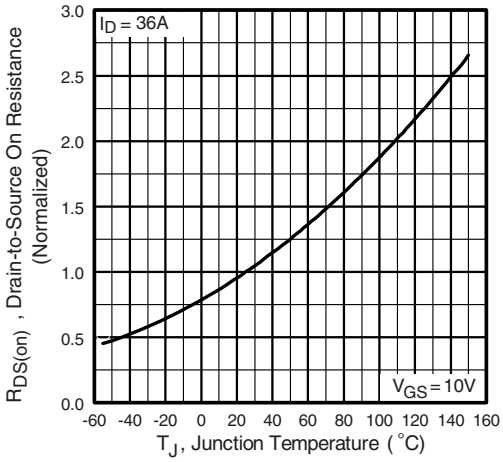


Fig. 4 - Normalized On-Resistance vs. Temperature

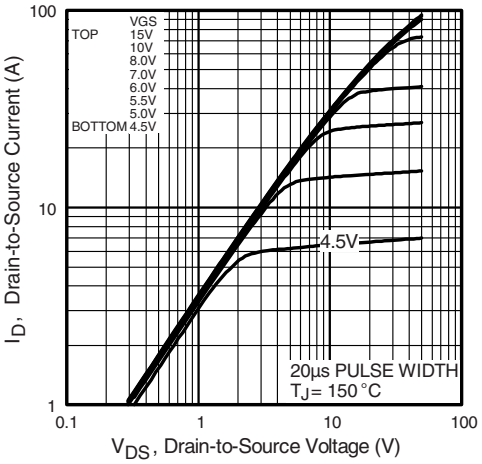


Fig. 2 - Typical Output Characteristics

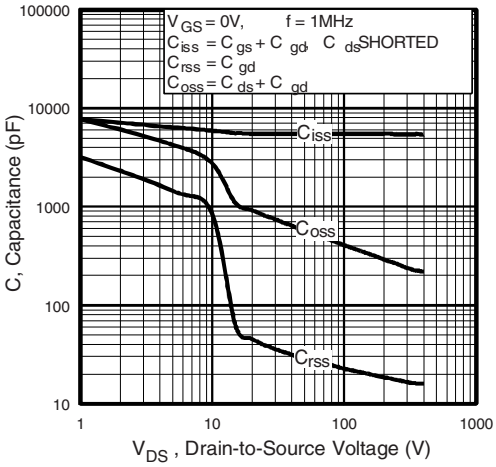


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

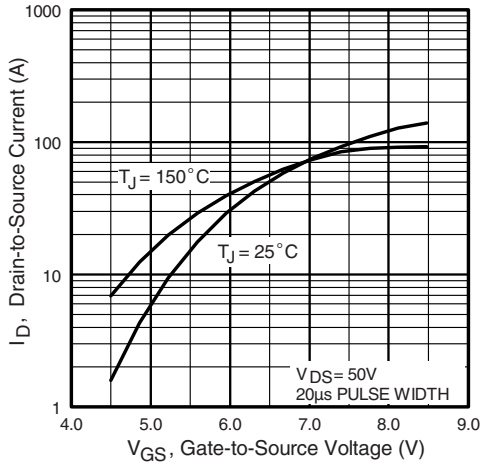


Fig. 3 - Typical Transfer Characteristics

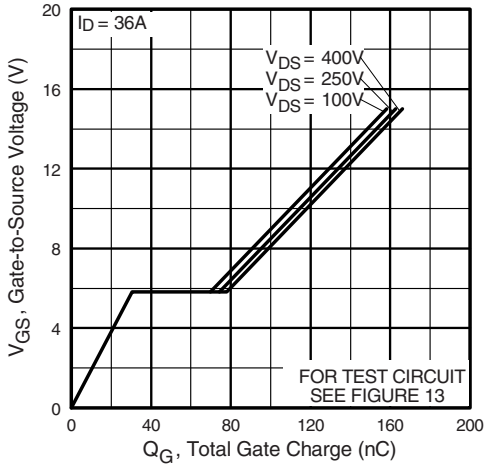


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

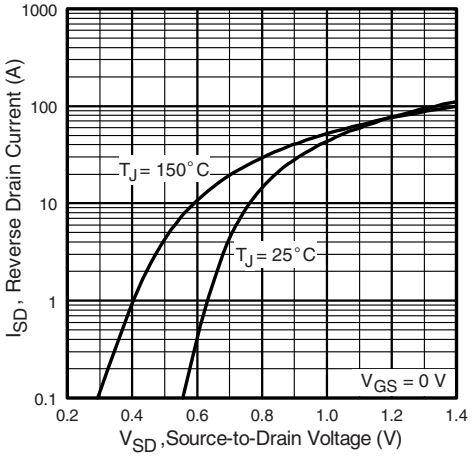


Fig. 7 - Typical Source-Drain Diode Forward Voltage

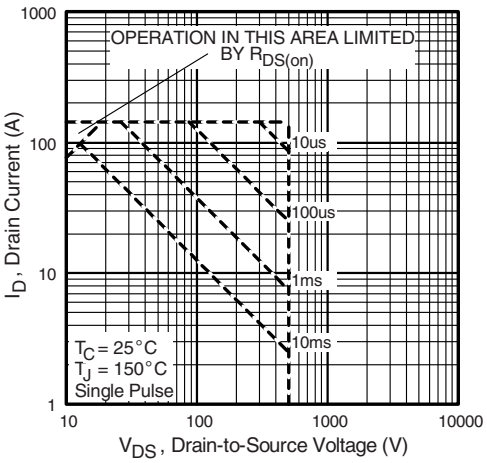


Fig. 8 - Maximum Safe Operating Area

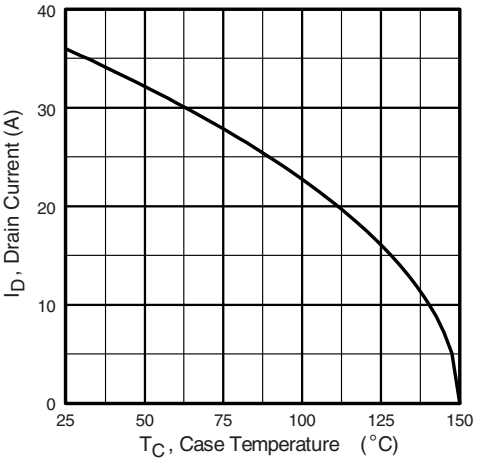


Fig. 9 - Maximum Drain Current vs. Case Temperature

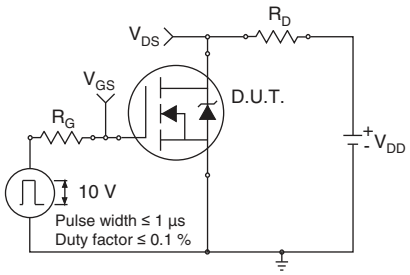


Fig. 10a - Switching Time Test Circuit

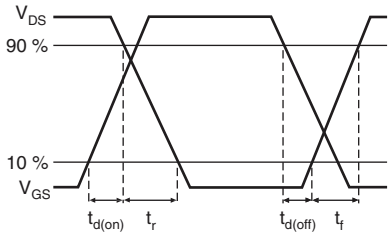


Fig. 10b - Switching Time Waveforms

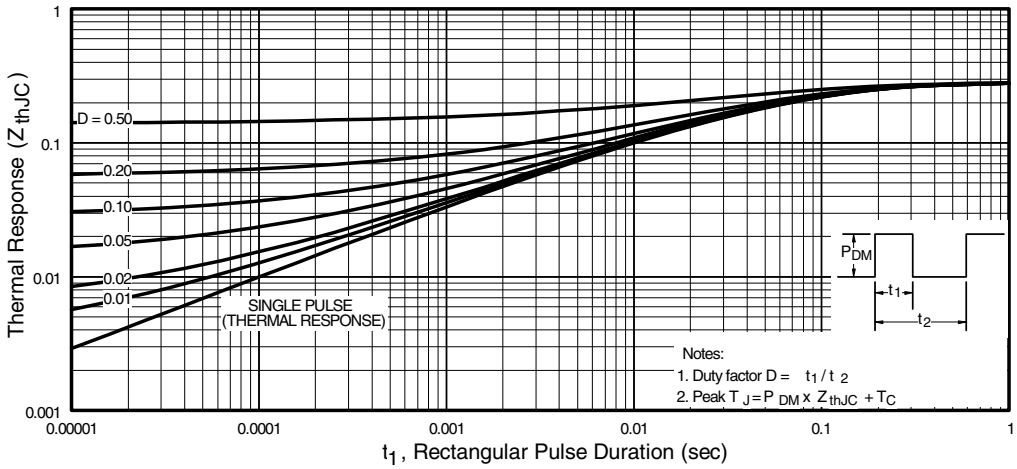


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

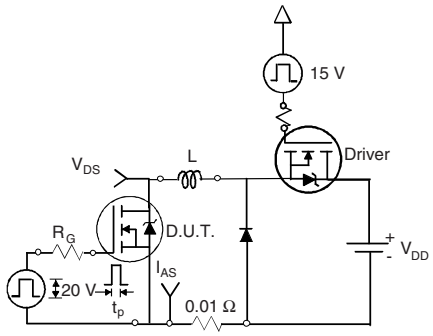


Fig. 12a - Unclamped Inductive Test Circuit

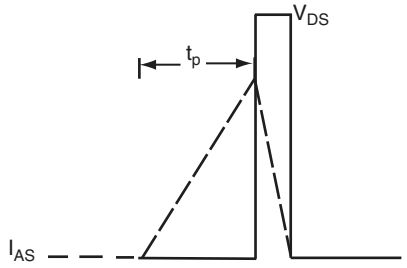


Fig. 12b - Unclamped Inductive Waveforms

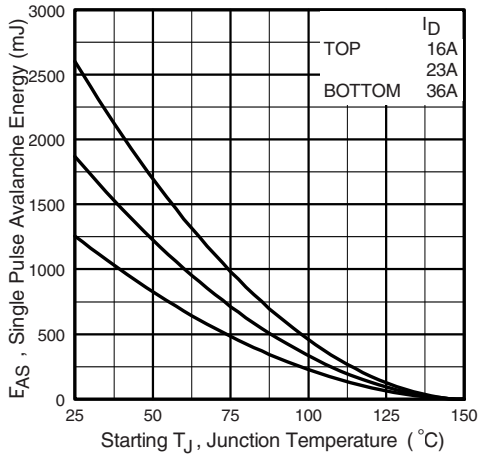


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

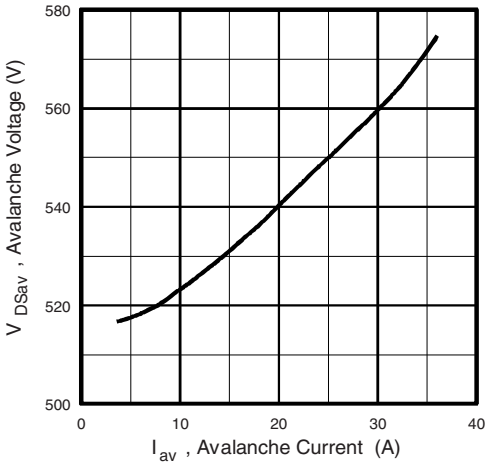


Fig. 12d - Maximum Avalanche Energy vs. Drain Current

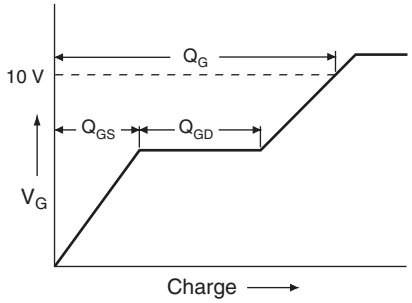


Fig. 13a - Basic Gate Charge Waveform

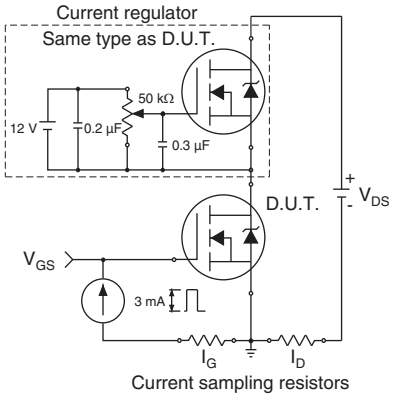
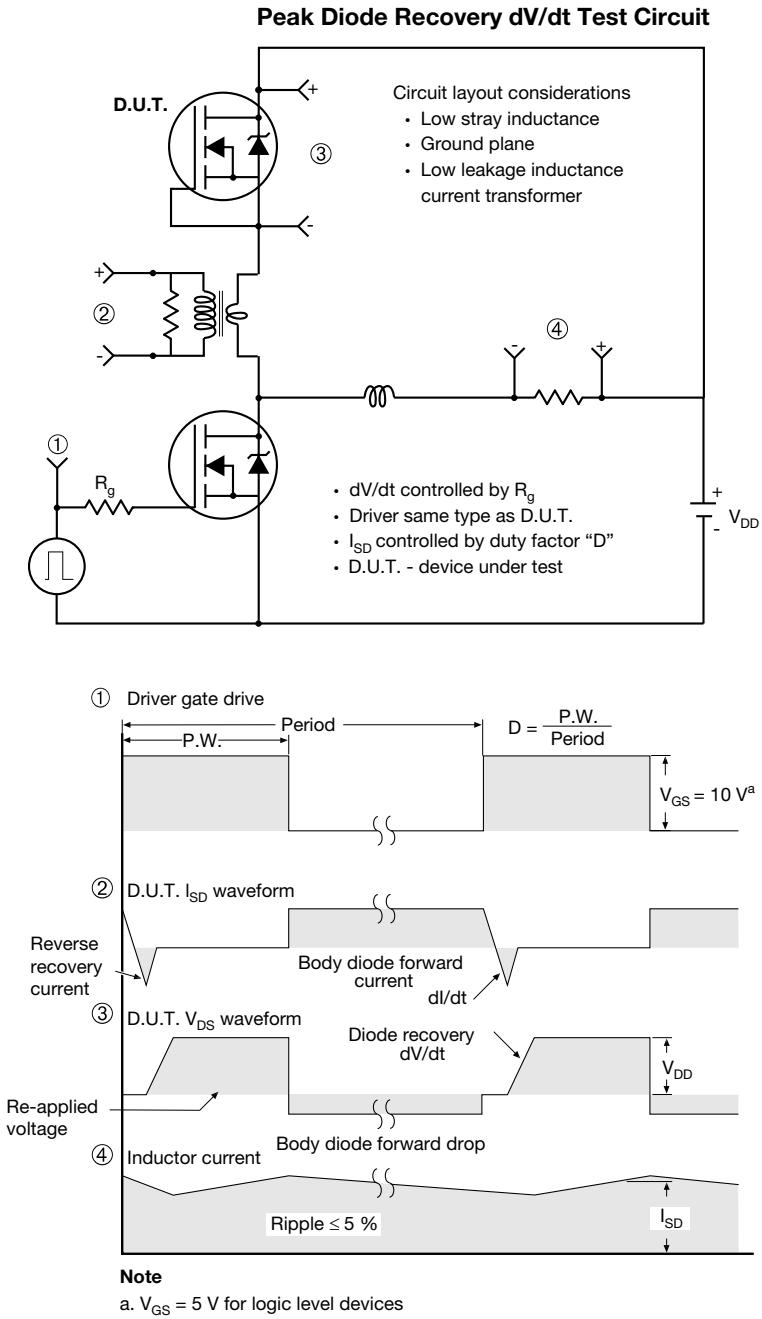


Fig. 13b - Gate Charge Test Circuit



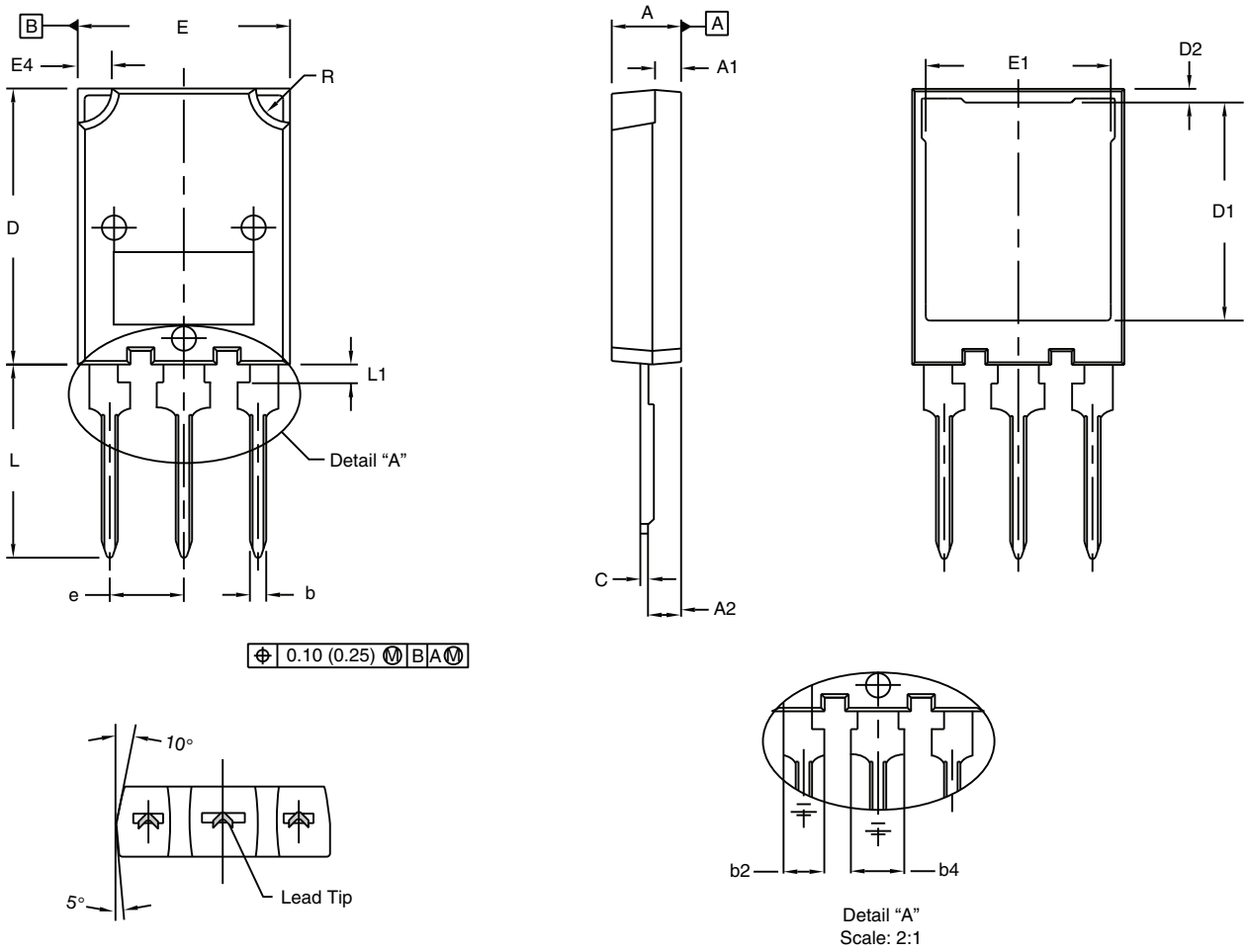
Note

a. V_{GS} = 5 V for logic level devices

Fig. 14 - For N-Channel

TO-274AA (High Voltage)

VERSION 1: FACILITY CODE = Y



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.70	5.30	0.185	0.209
A1	1.50	2.50	0.059	0.098
A2	2.25	2.65	0.089	0.104
b	1.30	1.60	0.051	0.063
b2	1.80	2.20	0.071	0.087
b4	3.00	3.25	0.118	0.128
c (1)	0.38	0.89	0.015	0.035
D	19.80	20.80	0.780	0.819

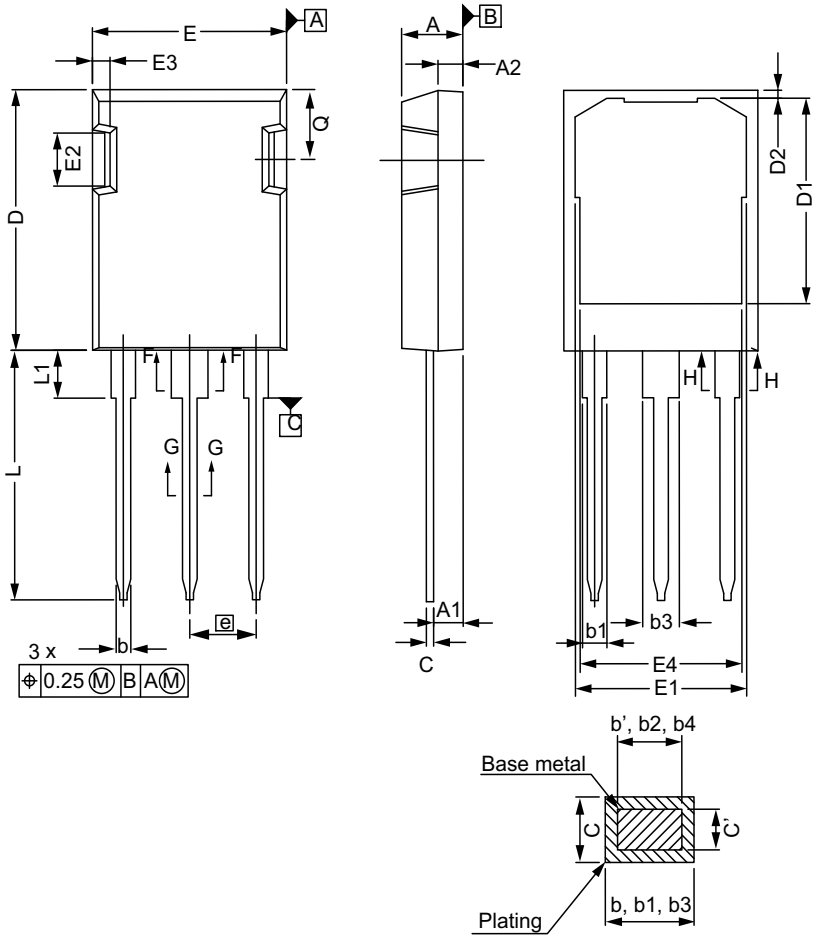
	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	15.50	16.10	0.610	0.634
D2	0.70	1.30	0.028	0.051
E	15.10	16.10	0.594	0.634
E1	13.30	13.90	0.524	0.547
e	5.45 BSC		0.215 BSC	
L	13.70	14.70	0.539	0.579
L1	1.00	1.60	0.039	0.063
R	2.00	3.00	0.079	0.118

Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outer extremes of the plastic body
- Outline conforms to JEDEC® outline to TO-274AA

(1) Dimension measured at tip of lead

VERSION 2: FACILITY CODE = N



SECTION "F-F", "G-G" AND "H-H"
SCALE: NONE

	MILLIMETERS	
DIM.	MIN.	MAX.
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	1.91	2.41
b2	1.91	2.16
b3	2.87	3.38
b4	2.87	3.13
c'	0.55	0.65
c	0.55	0.68
D	20.80	21.10

	MILLIMETERS	
DIM.	MIN.	MAX.
D1	16.25	17.65
D2	0.50	0.80
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	5.44 BSC	
N	3	
L	19.81	20.32
L1	3.70	4.00
Q	5.49	6.00

ECN: E20-0538-Rev. C, 19-Oct-2020
DWG: 5975

Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- Outline conforms to JEDEC® outline to TO-274AD
- Dimensions are measured in mm, angles are in degree
- Metal surfaces are tin plated, except area of cut

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